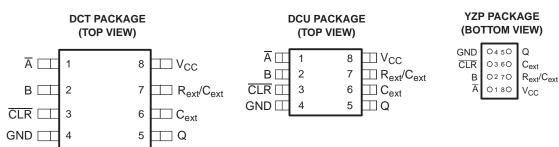


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FEATURES

- Available in the Texas Instruments NanoFree[™] Package
- Supports 5-V V_{CC} Operation .
- Inputs Accept Voltages to 5.5 V •
- Max t_{pd} of 8 ns at 3.3 V •
- Supports Mixed-Mode Voltage Operation on All Ports
- Schmitt-Trigger Circuitry on \overline{A} and B Inputs for Slow Input Transition Rates
- **Edge Triggered From Active-High or Active-Low Gated Logic Inputs**

- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- **Overriding Clear Terminates Output Pulse**
- **Glitch-Free Power-Up Reset on Outputs**
- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The SN74LVC1G123 is a single retriggerable monostable multivibrator designed for 1.65-V to 5.5-V V_{CC} operation.

This monostable multivibrator features output pulse-duration control by three methods. In the first method, the \overline{A} input is low, and the B input goes high. In the second method, the B input is high, and the \overline{A} input goes low. In the third method, the \overline{A} input is low, the B input is high, and the clear (\overline{CLR}) input goes high.

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74LVC1G123YZPR	D8_
–40°C to 85°C	SSOP - DCT	Reel of 3000	SN74LVC1G123DCTR	C 22
		Reel of 250	SN74LVC1G123DCTT	C23_
	VSSOP – DCU	Reel of 3000	SN74LVC1G123DCUR	C02
	V350F - DC0	Reel of 250	SN74LVC1G123DCUT	C23_

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site. DCU: The actual top-side marking has one additional character that designates the assembly/test site. YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. NanoFree is a trademark of Texas Instruments.



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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The output pulse duration is programmed by selecting external resistance and capacitance values. The external timing capacitor must be connected between C_{ext} and R_{ext}/C_{ext} (positive) and an external resistor connected between R_{ext}/C_{ext} and V_{CC} . To obtain variable pulse durations, connect an external variable resistance between R_{ext}/C_{ext} and V_{CC} . The output pulse duration also can be reduced by taking \overline{CLR} low.

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. The \overline{A} and B inputs have Schmitt triggers with sufficient hysteresis to handle slow input transition rates with jitter-free triggering at the outputs.

Once triggered, the basic pulse duration can be extended by retriggering the gated low-level-active (\overline{A}) or high-level-active (B) input. Pulse duration can be reduced by taking \overline{CLR} low. \overline{CLR} can be used to override \overline{A} or B inputs. The input/output timing diagram illustrates pulse control by retriggering the inputs and early clearing.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

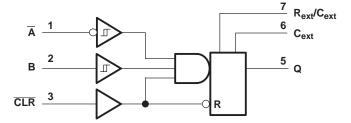
NanoFree[™] package technology is a major breakthrough in IC packaging concepts, using the die as the package.

	INPUTS		OUTPUTS
CLR	Ā	в	Q
L	Х	Х	L
Х	Н	Х	L ⁽¹⁾
Х	Х	L	L ⁽¹⁾
Н	L	\uparrow	Л
Н	\downarrow	Н	Л
Ŷ	L	н	Л

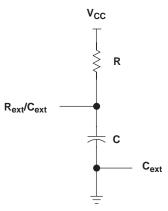
FUNCTION TABLE

 These outputs are based on the assumption that the indicated steady-state conditions at the A and B inputs have been set up long enough to complete any pulse started before the setup.

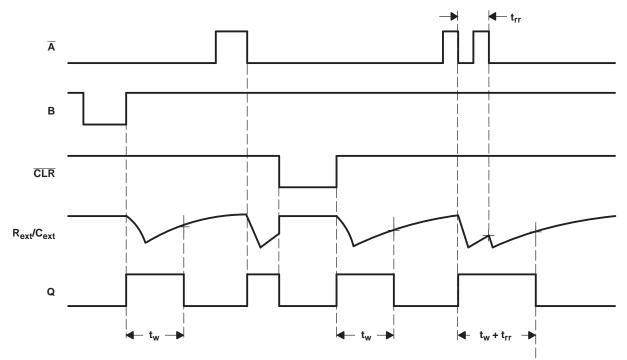
LOGIC DIAGRAM (POSITIVE LOGIC)



REQUIRED TIMING CIRCUIT



INPUT/OUTPUT TIMING DIAGRAM



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾	ut voltage range ⁽²⁾			V
Vo	Voltage range applied to any output in the	pltage range applied to any output in the high-impedance or power-off state ⁽²⁾		6.5	V
Vo	Voltage range applied to any output in the	ne high or low state ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND)		±100	mA
		DCT package		220	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DCU package		227	°C/W
		YZP package		102	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
\/	Supply voltage	Operating	1.65	5.5	V
V _{CC}	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
. ,	LPade Jacob Construction Review	V_{CC} = 2.3 V to 2.7 V	1.7		
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	2		V
		V_{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
		V_{CC} = 2.3 V to 2.7 V		0.7	V
V _{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		0.8	v
		V_{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
I _{OH}	High-level output current			-16	mA
		$V_{CC} = 3 V$		-24	
		$V_{CC} = 4.5 V$		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I _{OL}	Low-level output current			16	mA
		$V_{CC} = 3 V$		24	
		V _{CC} = 4.5 V		32	
D (2)	External timing registeres	$V_{CC} = 2 V$	5 k		0
R _{ext} ⁽²⁾	External timing resistance	$V_{CC} \ge 3 V$	1 k		Ω
T _A	Operating free-air temperature		-40	85	°C

All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
R_{ext}/C_{ext} is an I/O and must not be connected directly to GND or V_{CC}.

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

F	PARAMETER	TES	T CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT
		I _{OH} = −100 μA		1.65 V to 5.5 V	V _{CC} - 0.1			
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
V		I _{OH} = -8 mA		2.3 V	1.9			
V _{OH}		I _{OH} = -16 mA		2.1/	2.4			V
		I _{OH} = -24 mA		3 V	2.3			
		I _{OH} = -32 mA		4.5 V	3.8			
		I _{OL} = 100 μA		1.65 V to 5.5 V			0.1	
		I _{OL} = 4 mA		1.65 V			0.45	
V		I _{OL} = 8 mA		2.3 V			0.3	V
V _{OL}		I _{OL} = 16 mA		2.1/			0.4	V
		I _{OL} = 24 mA		3 V			0.55	
		I _{OL} = 32 mA		4.5 V			0.55	
	R _{ext} /C _{ext} ⁽²⁾	B = GND,	$\overline{A} = \overline{CLR} = V_{CC}$				±0.25	A
I _I	Ā, B, CLR	$V_{I} = 5.5 \text{ V or GND}$		1.65 V to 5.5 V			±1	μA
I _{off}	Ā, B, Q, CLR	$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$		0			±10	μΑ
I _{CC}	Quiescent	$V_{I} = V_{CC}$ or GND,	$I_0 = 0$	5.5 V			20	μΑ
				1.65 V			165	
				2.3 V			220	
I _{CC}	Active state	$V_I = V_{CC}$ or GND,	$R_{ext}/C_{ext} = 0.5 V_{CC}$	3 V			280	μΑ
				4.5 V			650	
				5.5 V			975	
CI		$V_{I} = V_{CC}$ or GND		3.3 V		3		pF

TEXAS

STRUMENTS www.ti.com

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		TEST CO	TEST CONDITIONS		V_{CC} = 1.8 V ± 0.15 V		2.5 V 2 V	$\begin{array}{c} \mathrm{V_{CC}=3.3~V}\\ \pm~0.3~\mathrm{V} \end{array}$		$V_{CC} = 5 V \\ \pm 0.5 V$		UNIT	
					MIN	TYP	MIN	TYP	MIN	TYP	MIN	TYP	
+ INI	Pulse duration	CLR			8		4		3		2.5		20
t _w IN	Fuise duration	A or B trigger			8		4		3		2.5		ns
			$P = 1 k \Omega$	$C_{ext} = 100 \text{ pF}$						5.5		4.5	ns
+	Dulaa ratriggar tima		$R_{ext} = 1 K \Omega$	$C_{ext} = 100 \text{ pF}$ $C_{ext} = 100 \text{ \muF}$						1.4		1.1	μs
۲r	Pulse retrigger time			$C_{ext} = 100 \text{ pF}$ $C_{ext} = 100 \text{ \muF}$		75		45					ns
			$R_{ext} = 5 RS2$	C_{ext} = 100 μ F		1.8		1.4					μs

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT)		۷ _C	_C = 1.8 [°] 0.15 V	V	V _{CC} = ± 0.2		V _{CC} = ± 0.3		= V _{CC} ± 0.5	5 V 5 V	UNIT
		(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Ā or B		7	18.5	52	4	17	3	11.5	2	7.6	
t _{pd}	CLR	Q	5	12.4	34	3	11.5	2	8	1.5	5.5	ns
	CLR trigger		7	17.4	54	4	15.5	3	10.5	2	7	

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Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM TO		TEST CONDITIONS		V _{CC} = 1.8 V ± 0.15 V		$\begin{array}{c} V_{CC} \texttt{= 2.5 V} \\ \pm \ \texttt{0.2 V} \end{array}$		V_{CC} = 3.3 V ± 0.3 V		$V_{CC} = 5 V \\ \pm 0.5 V$		UNIT
	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP ⁽¹⁾	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Ā or B			6	18.6	57	3	18.5	2	12.5	1.5	8.2	
t _{pd}	CLR	Q		4	11.6	36.5	2	12.5	1.5	8.6	1.5	6	ns
	CLR trigger			5	17.3	59	2.5	17	2	11.5	1.5	7.5	
			$C_{ext} = 28 \text{ pF},$ $R_{ext} = 2 \text{ k}\Omega$		225	600	190	220	170	200	150	180	ns
t _w OUT ⁽²⁾		Q	$\begin{array}{l} C_{ext} = 0.01 \; \mu \text{F}, \\ \text{R}_{ext} = 10 \; \text{k} \Omega \end{array}$		100	110	100	110	100	110	100	110	μs
			$\begin{array}{l} C_{ext} = 0.1 \ \mu\text{F}, \\ R_{ext} = 10 \ \text{k}\Omega \end{array}$		1	1.1	1	1.1	1	1.1	1	1.1	ms

(1) $T_A = 25^{\circ}C$ (2) $t_w =$ Duration of pulse at Q output

Operating Characteristics

 $T_A = 25^{\circ}C$

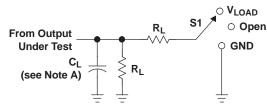
	PARAMETER	TEST CONDITIONS		V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	V _{CC} = 5 V TYP	UNIT
<u> </u>	Power dissipation	$\overline{A} = low, B = high,$	$R_{ext} = 1 k\Omega,$ No C_{ext}			35	37	~F
Cpo	capacitance	CLR = 10 MHz	$R_{ext} = 5 k\Omega,$ No C_{ext}	41	40			pF





Vı

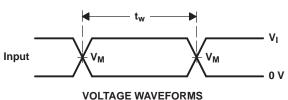
PARAMETER MEASUREMENT INFORMATION



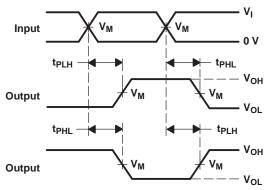
TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

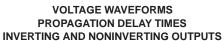
LOAD	CIRCUIT	

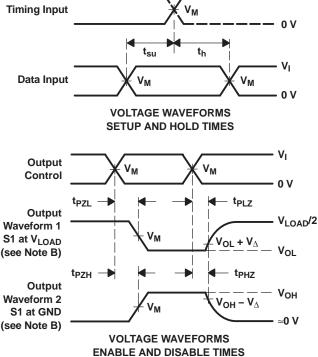
N	INPUTS		N	N	•		V
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	RL	V_{Δ}
$\textbf{1.8 V} \pm \textbf{0.15 V}$	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	15 pF	1 Μ Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	15 pF	1 MΩ	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	1 MΩ	0.3 V
5 V \pm 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	$2 \times V_{CC}$	15 pF	1 Μ Ω	0.3 V



PULSE DURATION







LOW- AND HIGH-LEVEL ENABLING

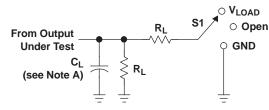
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
 - D. The outputs are measured one at a time, with one transition per measurement.

 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

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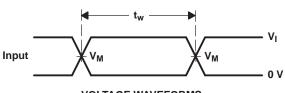
PARAMETER MEASUREMENT INFORMATION



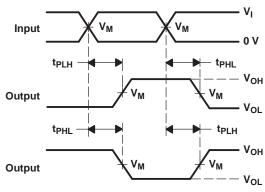
TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD	CIRCUIT

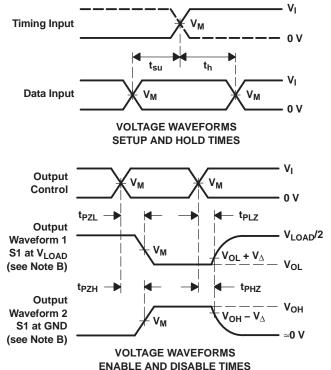
N	INPUTS		N	N	•	P	V
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	RL	V_{Δ}
$1.8~V\pm0.15~V$	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_{L} includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

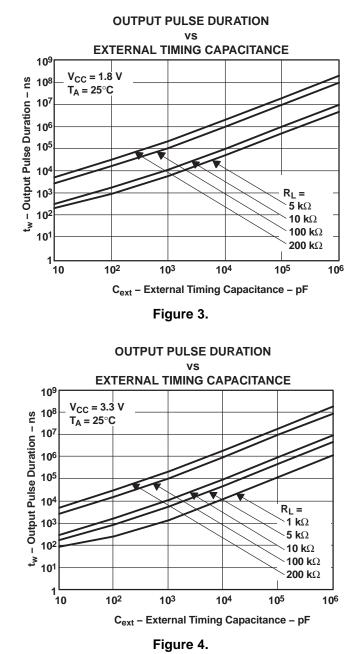
Figure 2. Load Circuit and Voltage Waveforms

Submit Documentation Feedback



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APPLICATION INFORMATION(1)



(1) Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

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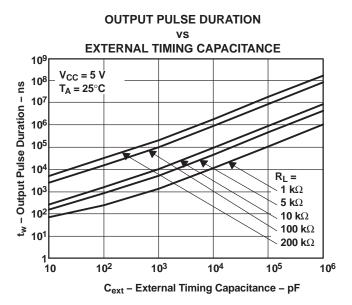


Figure 5.

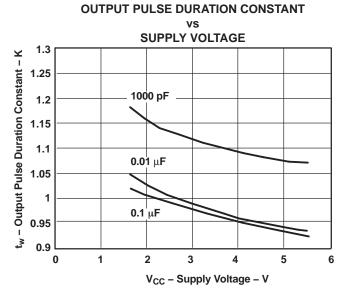


Figure 6.

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MINIMUM RETRIGGER TIME vs SUPPLY VOLTAGE 10 Minimum Retrigger Time – µs **0.01** μF 1 1000 pF 100 pF 0.1 10 pF 0.01 1.65 2.3 3 5.5 3.3 4.5 5 V_{CC} – Supply Voltage – V



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVC1G123DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCTRG4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCTTE4	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCTTG4	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCUTE4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCUTG4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTT	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUT	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



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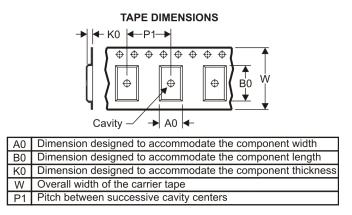
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G123DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

30-Jul-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G123DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	220.0	220.0	34.0

MECHANICAL DATA

MPDS049B - MAY 1999 - REVISED OCTOBER 2002

DCT (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion

D. Falls within JEDEC MO-187 variation DA.



DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



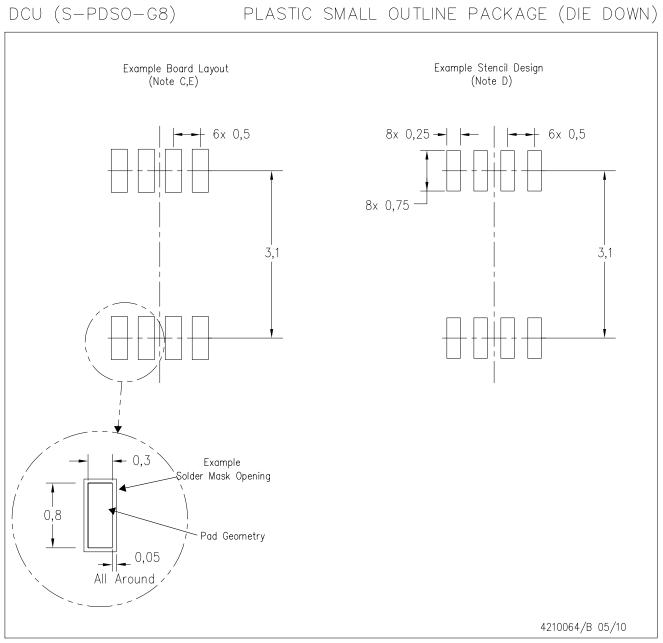
NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

D. Falls within JEDEC MO-187 variation CA.





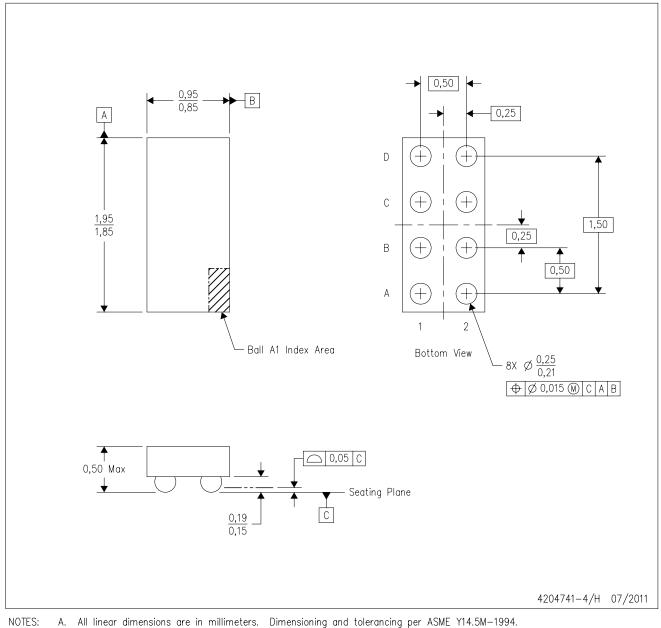
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



B. This drawing is subject to change without notice.

- C. NanoFree™ package configuration.
- D. This package is a Pb-free solder ball design. Refer to the 8 YEP package (drawing 4204725) for tin-lead (SnPb).

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